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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	17
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1829t-i-ss

TABLE 1-2: PIC16(L)F1825 PINOUT DESCRIPTION

Name	Function	Input Type	Output Type	Description
RA0/AN0/CPS0/C1IN+/VREF-/ DACOUT/TX(1)/CK(1)/ ICSPDAT/ICDDAT	RA0	TTL	CMOS	General purpose I/O.
	AN0	AN	—	A/D Channel 0 input.
	CPS0	AN	—	Capacitive sensing input 0.
	C1IN+	AN	—	Comparator C1 positive input.
	VREF-	AN	—	A/D and DAC Negative Voltage Reference input.
	DACOUT	—	AN	Digital-to-Analog Converter output.
	TX	—	CMOS	USART asynchronous transmit.
	CK	ST	CMOS	USART synchronous clock.
	ICSPDAT	ST	CMOS	ICSP™ Data I/O.
	ICDDAT	ST	CMOS	In-Circuit Data I/O.
RA1/AN1/CPS1/C12IN0-/VREF+/ SRI/RX(1)/DT(1)/ICSPCLK/ ICDCLK	RA1	TTL	CMOS	General purpose I/O.
	AN1	AN	—	A/D Channel 1 input.
	CPS1	AN	—	Capacitive sensing input 1.
	C12IN0-	AN	—	Comparator C1 or C2 negative input.
	VREF+	AN	—	A/D and DAC Positive Voltage Reference input.
	SRI	ST	—	SR Latch input.
	RX	ST	—	USART asynchronous input.
	DT	ST	CMOS	USART synchronous data.
	ICSPCLK	ST	—	Serial Programming Clock.
	ICDCLK	ST	—	In-Circuit Debug Clock.
RA2/AN2/CPS2/T0CKI/INT/ C1OUT/SRQ/CCP3/FLT0	RA2	ST	CMOS	General purpose I/O.
	AN2	AN	—	A/D Channel 2 input.
	CPS2	AN	—	Capacitive sensing input 2.
	T0CKI	ST	—	Timer0 clock input.
	INT	ST	—	External interrupt.
	C1OUT	—	CMOS	Comparator C1 output.
	SRQ	—	CMOS	SR Latch non-inverting output.
	CCP3	ST	CMOS	Capture/Compare/PWM3.
	FLT0	ST	—	ECCP Auto-Shutdown Fault input.
RA3/$\overline{SS1}$(1)/T1G(1)/VPP/$\overline{MCLR}$	RA3	TTL	—	General purpose input.
	$\overline{SS1}$	ST	—	Slave Select input.
	T1G	ST	—	Timer1 Gate input.
	VPP	HV	—	Programming voltage.
	$\overline{MCLR}$	ST	—	Master Clear with internal pull-up.

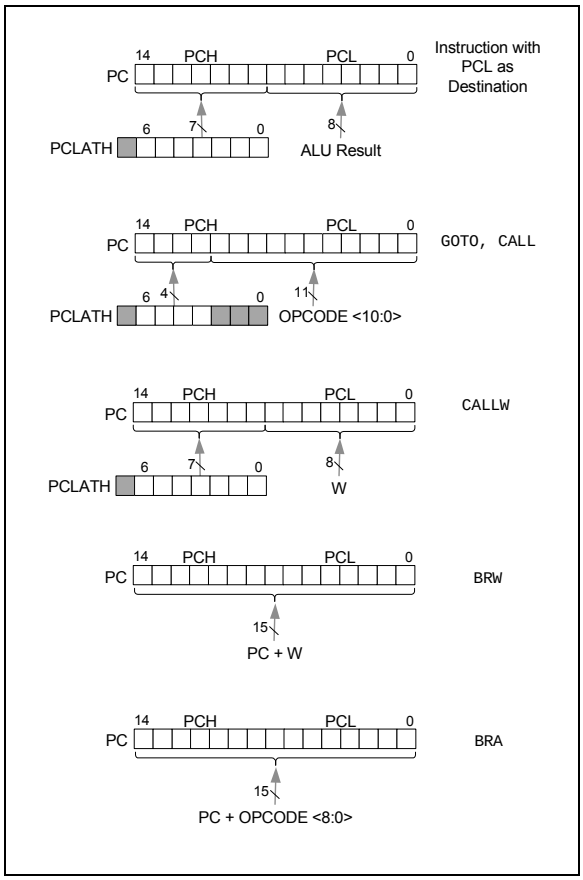
Legend: AN = Analog input or output CMOS = CMOS compatible input or output OD = Open Drain
TTL = TTL compatible input ST = Schmitt Trigger input with CMOS levels I^2C™ = Schmitt Trigger input with I^2C levels
HV = High Voltage XTAL = Crystal

Note 1: Pin functions can be moved using the APFCON0 or APFCON1 register.
2: Default function location.

3.3 PCL and PCLATH

The Program Counter (PC) is 15 bits wide. The low byte comes from the PCL register, which is a readable and writable register. The high byte (PC<14:8>) is not directly readable or writable and comes from PCLATH. On any Reset, the PC is cleared. Figure 3-3 shows the five situations for the loading of the PC.

FIGURE 3-3: LOADING OF PC IN DIFFERENT SITUATIONS



3.3.1 MODIFYING PCL

Executing any instruction with the PCL register as the destination simultaneously causes the Program Counter PC<14:8> bits (PCH) to be replaced by the contents of the PCLATH register. This allows the entire contents of the program counter to be changed by writing the desired upper seven bits to the PCLATH register. When the lower eight bits are written to the PCL register, all 15 bits of the program counter will change to the values contained in the PCLATH register and those being written to the PCL register.

3.3.2 COMPUTED GOTO

A computed GOTO is accomplished by adding an offset to the program counter (ADDWF PCL). When performing a table read using a computed GOTO method, care should be exercised if the table location crosses a PCL memory boundary (each 256-byte block). Refer to the Application Note AN556, *"Implementing a Table Read"* (DS00556).

3.3.3 COMPUTED FUNCTION CALLS

A computed function CALL allows programs to maintain tables of functions and provide another way to execute state machines or look-up tables. When performing a table read using a computed function CALL, care should be exercised if the table location crosses a PCL memory boundary (each 256-byte block).

If using the CALL instruction, the PCH<2:0> and PCL registers are loaded with the operand of the CALL instruction. PCH<6:3> is loaded with PCLATH<6:3>.

The CALLW instruction enables computed calls by combining PCLATH and W to form the destination address. A computed CALLW is accomplished by loading the W register with the desired address and executing CALLW. The PCL register is loaded with the value of W and PCH is loaded with PCLATH.

3.3.4 BRANCHING

The branching instructions add an offset to the PC. This allows relocatable code and code that crosses page boundaries. There are two forms of branching, BRW and BRA. The PC will have incremented to fetch the next instruction in both cases. When using either branching instruction, a PCL memory boundary may be crossed.

If using BRW, load the W register with the desired unsigned address and execute BRW. The entire PC will be loaded with the address PC + 1 + W.

If using BRA, the entire PC will be loaded with PC + 1 +, the signed value of the operand of the BRA instruction.

5.3 Clock Switching

The system clock source can be switched between external and internal clock sources via software using the System Clock Select (SCS) bits of the OSCCON register. The following clock sources can be selected using the SCS bits:

- Default system oscillator determined by FOSC bits in Configuration Word 1
- Timer1 32 kHz crystal oscillator
- Internal Oscillator Block (INTOSC)

5.3.1 SYSTEM CLOCK SELECT (SCS) BITS

The System Clock Select (SCS) bits of the OSCCON register selects the system clock source that is used for the CPU and peripherals.

- When the SCS bits of the OSCCON register = 00, the system clock source is determined by value of the FOSC<2:0> bits in the Configuration Word 1.
- When the SCS bits of the OSCCON register = 01, the system clock source is the Timer1 oscillator.
- When the SCS bits of the OSCCON register = 1x, the system clock source is chosen by the internal oscillator frequency selected by the IRCF<3:0> bits of the OSCCON register. After a Reset, the SCS bits of the OSCCON register are always cleared.

Note:	Any automatic clock switch, which may occur from Two-Speed Start-up or Fail-Safe Clock Monitor, does not update the SCS bits of the OSCCON register. The user can monitor the OSTS bit of the OSCSTAT register to determine the current system clock source.

When switching between clock sources, a delay is required to allow the new clock to stabilize. These oscillator delays are shown in Table 5-1.

5.3.2 OSCILLATOR START-UP TIMER STATUS (OSTS) BIT

The Oscillator Start-up Timer Status (OSTS) bit of the OSCSTAT register indicates whether the system clock is running from the external clock source, as defined by the FOSC<2:0> bits in the Configuration Word 1, or from the internal clock source. In particular, OSTS indicates that the Oscillator Start-up Timer (OST) has timed out for LP, XT or HS modes. The OST does not reflect the status of the Timer1 Oscillator.

5.3.3 TIMER1 OSCILLATOR

The Timer1 Oscillator is a separate crystal oscillator associated with the Timer1 peripheral. It is optimized for timekeeping operations with a 32.768 kHz crystal connected between the T1OSO and T1OSI device pins.

The Timer1 oscillator is enabled using the T1OSCEN control bit in the T1CON register. See **Section 21.0 "Timer1 Module with Gate Control"** for more information about the Timer1 peripheral.

5.3.4 TIMER1 OSCILLATOR READY (T1OSCR) BIT

The user must ensure that the Timer1 Oscillator is ready to be used before it is selected as a system clock source. The Timer1 Oscillator Ready (T1OSCR) bit of the OSCSTAT register indicates whether the Timer1 oscillator is ready to be used. After the T1OSCR bit is set, the SCS bits can be configured to select the Timer1 oscillator.

TABLE 17-1: SUMMARY OF REGISTERS ASSOCIATED WITH THE DAC MODULE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on page
FVRCON	FVREN	FVRRDY	TSEN	TSRNG	CDAFVR<1:0>		ADFVR<1:0>		142
DACCON0	DACEN	DACLPS	DACOE	—	DACPSS<1:0>		—	DACNSS	160
DACCON1	—	—	—	DACR<4:0>					160

Legend: — Unimplemented, read as '0'. Shaded cells are unused by the DAC module.

22.1 Timer2/4/6 Operation

The clock input to the Timer2/4/6 modules is the system instruction clock (FOSC/4).

TMRx increments from 00h on each clock edge.

A 4-bit counter/prescaler on the clock input allows direct input, divide-by-4 and divide-by-16 prescale options. These options are selected by the prescaler control bits, TxCKPS<1:0> of the TxCON register. The value of TMRx is compared to that of the Period register, PRx, on each clock cycle. When the two values match, the comparator generates a match signal as the timer output. This signal also resets the value of TMRx to 00h on the next cycle and drives the output counter/postscaler (see **Section 22.2 "Timer2/4/6 Interrupt"**).

The TMRx and PRx registers are both directly readable and writable. The TMRx register is cleared on any device Reset, whereas the PRx register initializes to FFh. Both the prescaler and postscaler counters are cleared on the following events:

- a write to the TMRx register
- a write to the TxCON register
- Power-on Reset (POR)
- Brown-out Reset (BOR)
- $\overline{\text{MCLR}}$ Reset
- Watchdog Timer (WDT) Reset
- Stack Overflow Reset
- Stack Underflow Reset
- RESET Instruction

Note:	TMRx is not cleared when TxCON is written.

22.2 Timer2/4/6 Interrupt

Timer2/4/6 can also generate an optional device interrupt. The Timer2/4/6 output signal (TMRx-to-PRx match) provides the input for the 4-bit counter/postscaler. This counter generates the TMRx match interrupt flag which is latched in TMRxIF of the PIRx register. The interrupt is enabled by setting the TMRx Match Interrupt Enable bit, TMRxIE of the PIEx register.

A range of 16 postscale options (from 1:1 through 1:16 inclusive) can be selected with the postscaler control bits, TxOUTPS<3:0>, of the TxCON register.

22.3 Timer2/4/6 Output

The unscaled output of TMRx is available primarily to the CCP modules, where it is used as a time base for operations in PWM mode.

Timer2 can be optionally used as the shift clock source for the MSSPx modules operating in SPI mode. Additional information is provided in **Section 25.0 "Master Synchronous Serial Port (MSSP1 and MSSP2) Module"**.

22.4 Timer2/4/6 Operation During Sleep

The Timer2/4/6 timers cannot be operated while the processor is in Sleep mode. The contents of the TMRx and PRx registers will remain unchanged while the processor is in Sleep mode.

23.0 DATA SIGNAL MODULATOR

The Data Signal Modulator (DSM) is a peripheral which allows the user to mix a data stream, also known as a modulator signal, with a carrier signal to produce a modulated output.

Both the carrier and the modulator signals are supplied to the DSM module either internally, from the output of a peripheral, or externally through an input pin.

The modulated output signal is generated by performing a logical “AND” operation of both the carrier and modulator signals and then provided to the MDOUT pin.

The carrier signal is comprised of two distinct and separate signals. A carrier high (CARH) signal and a carrier low (CARL) signal. During the time in which the modulator (MOD) signal is in a logic high state, the DSM mixes the carrier high signal with the modulator signal. When the modulator signal is in a logic low state, the DSM mixes the carrier low signal with the modulator signal.

Using this method, the DSM can generate the following types of Key Modulation schemes:

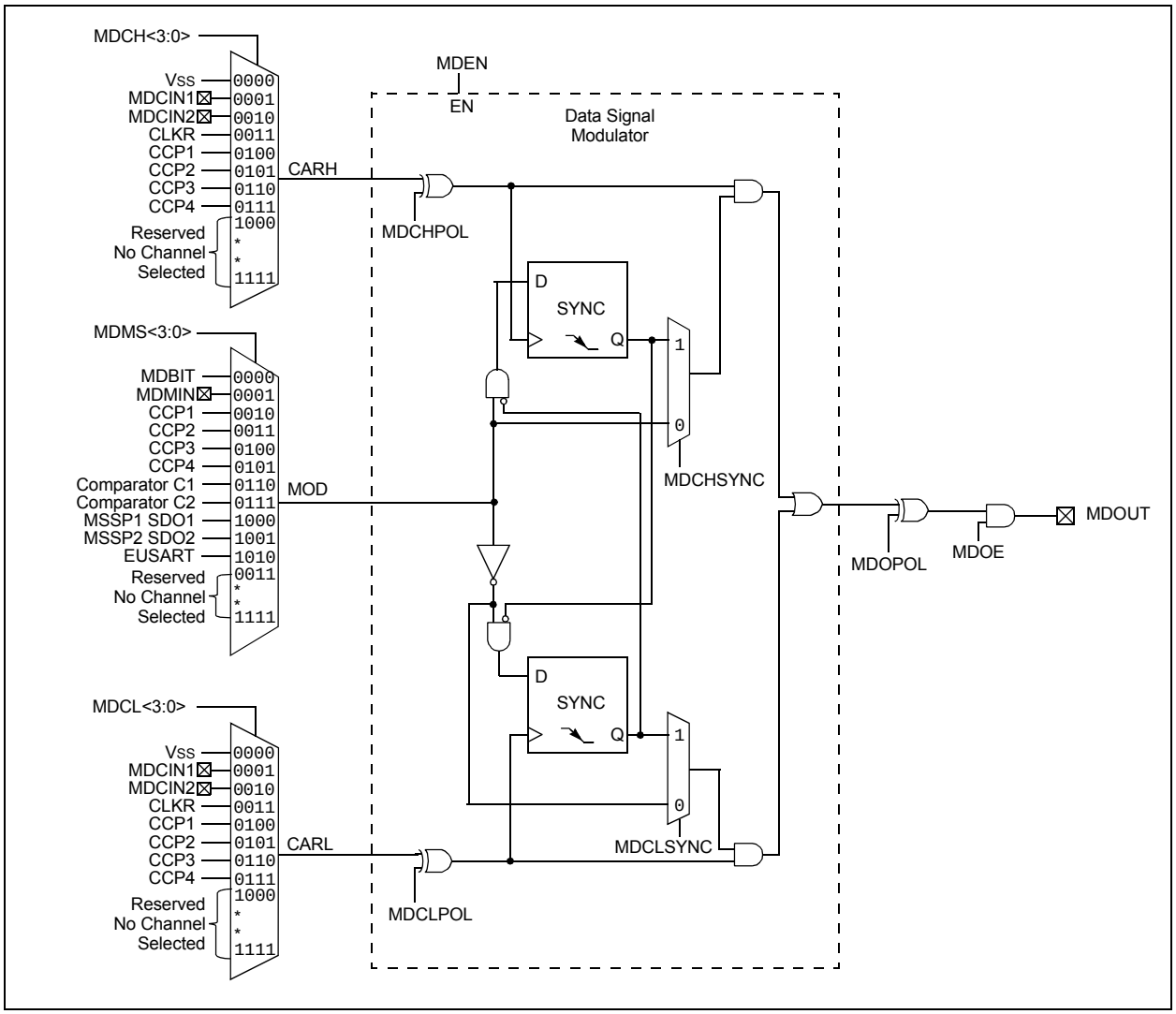
- Frequency-Shift Keying (FSK)
- Phase-Shift Keying (PSK)
- On-Off Keying (OOK)

Additionally, the following features are provided within the DSM module:

- Carrier Synchronization
- Carrier Source Polarity Select
- Carrier Source Pin Disable
- Programmable Modulator Data
- Modulator Source Pin Disable
- Modulated Output Polarity Select
- Slew Rate Control

Figure 23-1 shows a Simplified Block Diagram of the Data Signal Modulator peripheral.

FIGURE 23-1: SIMPLIFIED BLOCK DIAGRAM OF THE DATA SIGNAL MODULATOR



25.6.7 I²C MASTER MODE RECEPTION

Master mode reception (Figure 25-29) is enabled by programming the Receive Enable bit, RCEN bit of the SSPxCON2 register.

Note:	The MSSPx module must be in an Idle state before the RCEN bit is set or the RCEN bit will be disregarded.

The Baud Rate Generator begins counting and on each rollover, the state of the SCLx pin changes (high-to-low/low-to-high) and data is shifted into the SSPxSR. After the falling edge of the eighth clock, the receive enable flag is automatically cleared, the contents of the SSPxSR are loaded into the SSPxBUF, the BF flag bit is set, the SSPxIF flag bit is set and the Baud Rate Generator is suspended from counting, holding SCLx low. The MSSPx is now in Idle state awaiting the next command. When the buffer is read by the CPU, the BF flag bit is automatically cleared. The user can then send an Acknowledge bit at the end of reception by setting the Acknowledge Sequence Enable, ACKEN bit of the SSPxCON2 register.

25.6.7.1 BF Status Flag

In receive operation, the BF bit is set when an address or data byte is loaded into SSPxBUF from SSPxSR. It is cleared when the SSPxBUF register is read.

25.6.7.2 SSPOV Status Flag

In receive operation, the SSPOV bit is set when eight bits are received into the SSPxSR and the BF flag bit is already set from a previous reception.

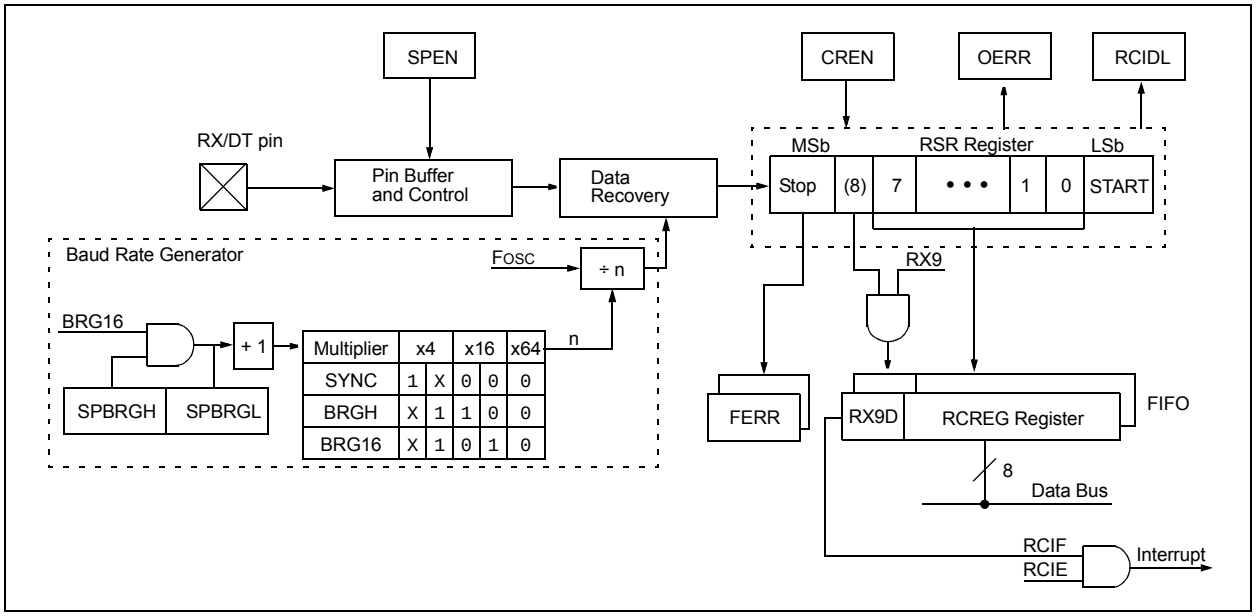
25.6.7.3 WCOL Status Flag

If the user writes the SSPxBUF when a receive is already in progress (i.e., SSPxSR is still shifting in a data byte), the WCOL bit is set and the contents of the buffer are unchanged (the write does not occur).

25.6.7.4 Typical Receive Sequence:

1. The user generates a Start condition by setting the SEN bit of the SSPxCON2 register.
2. SSPxIF is set by hardware on completion of the Start.
3. SSPxIF is cleared by software.
4. User writes SSPxBUF with the slave address to transmit and the R/$\overline{W}$ bit set.
5. Address is shifted out the SDAx pin until all eight bits are transmitted. Transmission begins as soon as SSPxBUF is written to.
6. The MSSPx module shifts in the $\overline{ACK}$ bit from the slave device and writes its value into the ACKSTAT bit of the SSPxCON2 register.
7. The MSSPx module generates an interrupt at the end of the ninth clock cycle by setting the SSPxIF bit.
8. User sets the RCEN bit of the SSPxCON2 register and the Master clocks in a byte from the slave.
9. After the eighth falling edge of SCLx, SSPxIF and BF are set.
10. Master clears SSPxIF and reads the received byte from SSPxUF, clears BF.
11. Master sets $\overline{ACK}$ value sent to slave in ACKDT bit of the SSPxCON2 register and initiates the $\overline{ACK}$ by setting the ACKEN bit.
12. Masters $\overline{ACK}$ is clocked out to the slave and SSPxIF is set.
13. User clears SSPxIF.
14. Steps 8-13 are repeated for each received byte from the slave.
15. Master sends a not $\overline{ACK}$ or Stop to end communication.

FIGURE 26-2: EUSART RECEIVE BLOCK DIAGRAM



The operation of the EUSART module is controlled through three registers:

- Transmit Status and Control (TXSTA)
- Receive Status and Control (RCSTA)
- Baud Rate Control (BAUDCON)

These registers are detailed in Register 26-1, Register 26-2 and Register 26-3, respectively.

When the receiver or transmitter section is not enabled then the corresponding RX or TX pin may be used for general purpose input and output.

26.1.2.4 Receive Framing Error

Each character in the receive FIFO buffer has a corresponding framing error Status bit. A framing error indicates that a Stop bit was not seen at the expected time. The framing error status is accessed via the FERR bit of the RCSTA register. The FERR bit represents the status of the top unread character in the receive FIFO. Therefore, the FERR bit must be read before reading the RCREG.

The FERR bit is read-only and only applies to the top unread character in the receive FIFO. A framing error (FERR = 1) does not preclude reception of additional characters. It is not necessary to clear the FERR bit. Reading the next character from the FIFO buffer will advance the FIFO to the next character and the next corresponding framing error.

The FERR bit can be forced clear by clearing the SPEN bit of the RCSTA register which resets the EUSART. Clearing the CREN bit of the RCSTA register does not affect the FERR bit. A framing error by itself does not generate an interrupt.

Note:	If all receive characters in the receive FIFO have framing errors, repeated reads of the RCREG will not clear the FERR bit.

26.1.2.5 Receive Overrun Error

The receive FIFO buffer can hold two characters. An overrun error will be generated if a third character, in its entirety, is received before the FIFO is accessed. When this happens the OERR bit of the RCSTA register is set. The characters already in the FIFO buffer can be read but no additional characters will be received until the error is cleared. The error must be cleared by either clearing the CREN bit of the RCSTA register or by resetting the EUSART by clearing the SPEN bit of the RCSTA register.

26.1.2.6 Receiving 9-bit Characters

The EUSART supports 9-bit character reception. When the RX9 bit of the RCSTA register is set the EUSART will shift nine bits into the RSR for each character received. The RX9D bit of the RCSTA register is the ninth and Most Significant data bit of the top unread character in the receive FIFO. When reading 9-bit data from the receive FIFO buffer, the RX9D data bit must be read before reading the eight Least Significant bits from the RCREG.

26.1.2.7 Address Detection

A special Address Detection mode is available for use when multiple receivers share the same transmission line, such as in RS-485 systems. Address detection is enabled by setting the ADDEN bit of the RCSTA register.

Address detection requires 9-bit character reception. When address detection is enabled, only characters with the ninth data bit set will be transferred to the receive FIFO buffer, thereby setting the RCIF interrupt bit. All other characters will be ignored.

Upon receiving an address character, user software determines if the address matches its own. Upon address match, user software must disable address detection by clearing the ADDEN bit before the next Stop bit occurs. When user software detects the end of the message, determined by the message protocol used, software places the receiver back into the Address Detection mode by setting the ADDEN bit.

28.2 Low-Voltage Programming Entry Mode

The Low-Voltage Programming Entry mode allows the PIC16(L)F1825/9 devices to be programmed using V_{DD} only, without high voltage. When the LVP bit of Configuration Word 2 is set to '1', the low-voltage ICSP programming entry is enabled. To disable the Low-Voltage ICSP mode, the LVP bit must be programmed to '0'.

Entry into the Low-Voltage Programming Entry mode requires the following steps:

1. $\overline{MCLR}$ is brought to V_{IL}.
2. A 32-bit key sequence is presented on ICSPDAT, while clocking ICSPCLK.

Once the key sequence is complete, $\overline{MCLR}$ must be held at V_{IL} for as long as Program/Verify mode is to be maintained.

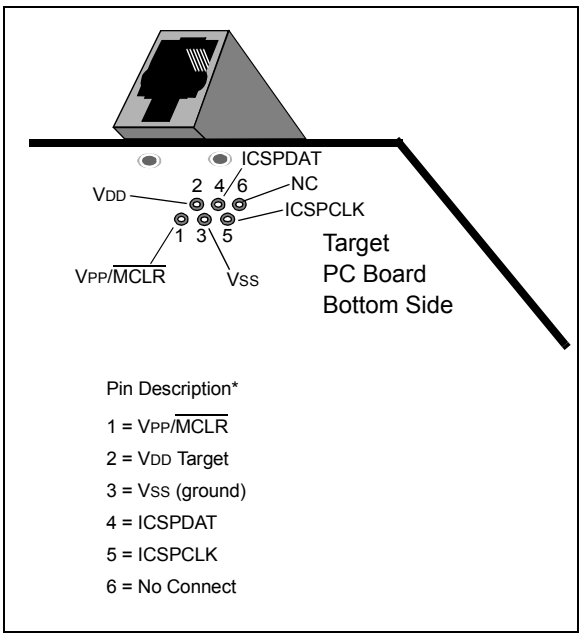
If low-voltage programming is enabled (LVP = 1), the $\overline{MCLR}$ Reset function is automatically enabled and cannot be disabled. See **Section 7.3 "MCLR"** for more information.

The LVP bit can only be reprogrammed to '0' by using the High-Voltage Programming mode.

28.3 Common Programming Interfaces

Connection to a target device is typically done through an ICSP™ header. A commonly found connector on development tools is the RJ-11 in the 6P6C (6-pin, 6 connector) configuration. See Figure 28-2.

FIGURE 28-2: ICD RJ-11 STYLE CONNECTOR INTERFACE



Another connector often found in use with the PICkit™ programmers is a standard 6-pin header with 0.1 inch spacing. Refer to Figure 28-3.

FIGURE 28-3: PICkit™ STYLE CONNECTOR INTERFACE

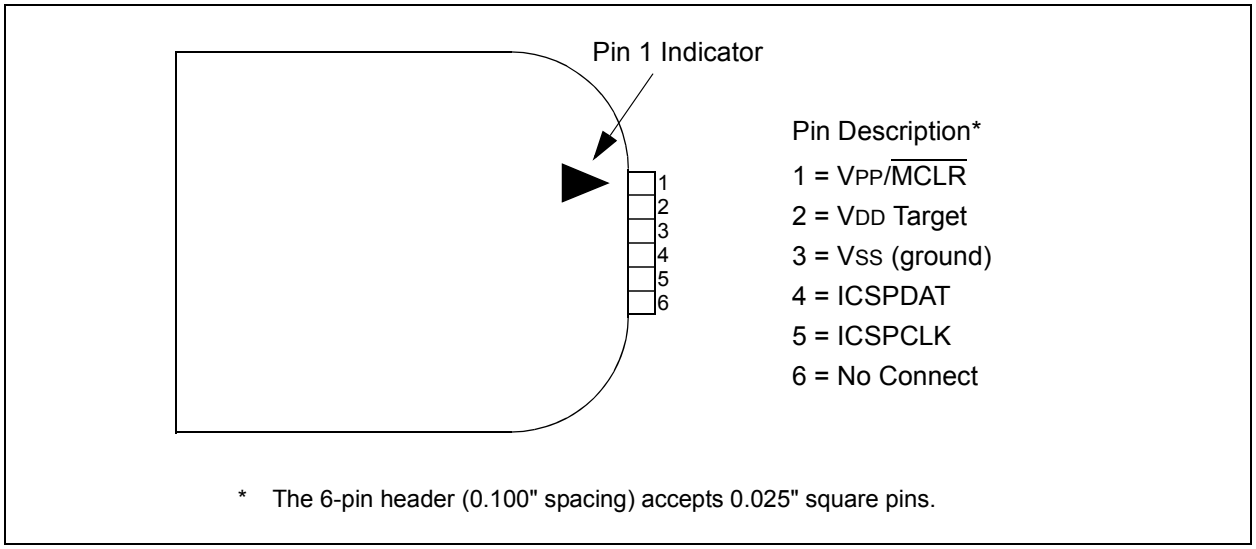


TABLE 29-3: PIC16(L)F1825/9 ENHANCED INSTRUCTION SET (CONTINUED)

Mnemonic, Operands		Description	Cycles	14-Bit Opcode MSb LSb	Status Affected	Notes
CONTROL OPERATIONS						
BRA	k	Relative Branch	2	11 001k kkkk kkkk		
BRW	–	Relative Branch with W	2	00 0000 0000 1011		
CALL	k	Call Subroutine	2	10 0kkk kkkk kkkk		
CALLW	–	Call Subroutine with W	2	00 0000 0000 1010		
GOTO	k	Go to address	2	10 1kkk kkkk kkkk		
RETFIE	k	Return from interrupt	2	00 0000 0000 1001		
RETLW	k	Return with literal in W	2	11 0100 kkkk kkkk		
RETURN	–	Return from Subroutine	2	00 0000 0000 1000		
INHERENT OPERATIONS						
CLRWDT	–	Clear Watchdog Timer	1	00 0000 0110 0100	$\overline{TO}$, $\overline{PD}$	
NOP	–	No Operation	1	00 0000 0000 0000		
OPTION	–	Load OPTION_REG register with W	1	00 0000 0110 0010		
RESET	–	Software device Reset	1	00 0000 0000 0001		
SLEEP	–	Go into Standby mode	1	00 0000 0110 0011	$\overline{TO}$, $\overline{PD}$	
TRIS	f	Load TRIS register with W	1	00 0000 0110 0fff		
C-COMPILER OPTIMIZED						
ADDFSR	n, k	Add Literal k to FSRn	1	11 0001 0nkk kkkk		
MOVIW	n mm	Move Indirect FSRn to W with pre/post inc/dec modifier, mm	1	00 0000 0001 0nmm	Z	**2, 3**
	k[n]	Move INDFn to W, Indexed Indirect.	1	11 1111 0nkk kkkk	Z	**2**
MOVWI	n mm	Move W to Indirect FSRn with pre/post inc/dec modifier, mm	1	00 0000 0001 1nmm		**2, 3**
	k[n]	Move W to INDFn, Indexed Indirect.	1	11 1111 1nkk kkkk		**2**

Note 1: If the Program Counter (PC) is modified, or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a NOP.

2: If this instruction addresses an INDF register and the MSb of the corresponding FSR is set, this instruction will require one additional instruction cycle.

3: See Table in the MOVIW and MOVWI instruction descriptions.

TABLE 30-4: CLKOUT AND I/O TIMING PARAMETERS

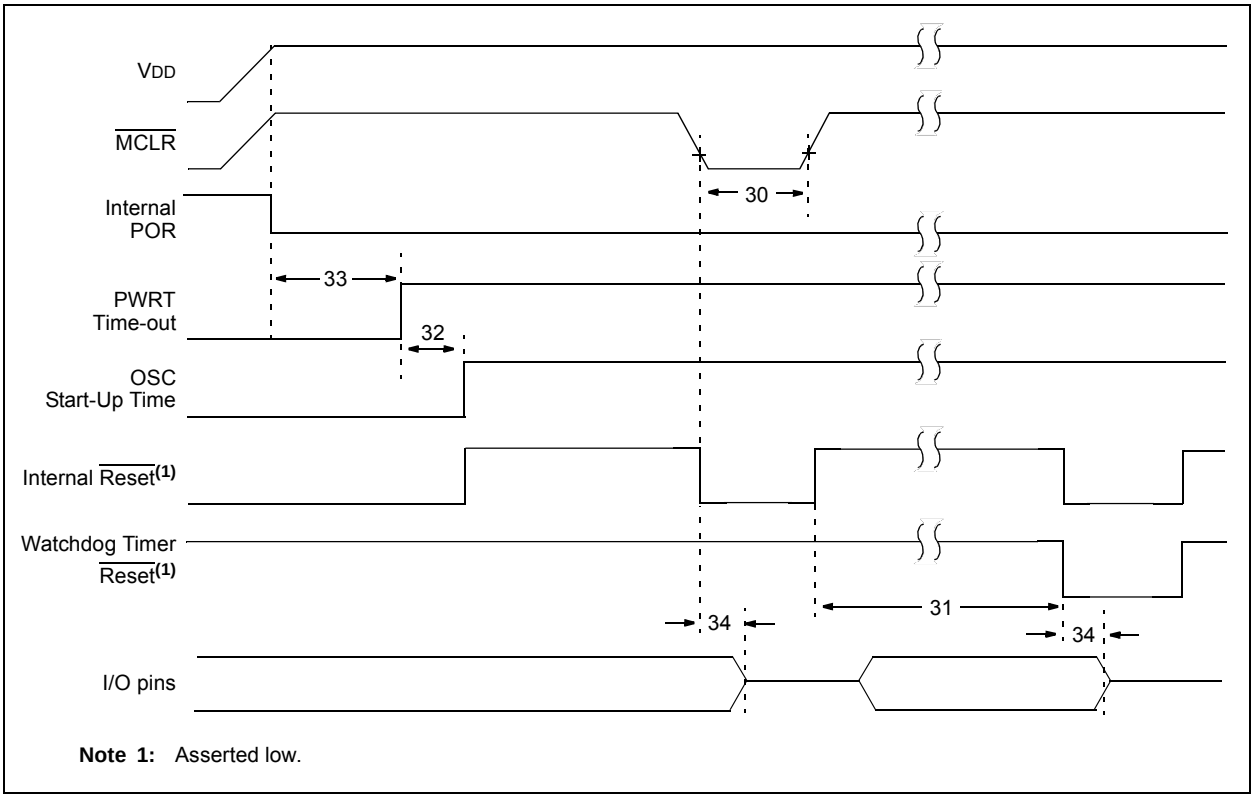
Standard Operating Conditions (unless otherwise stated) Operating Temperature -40°C ≤ TA ≤ +125°C							
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
OS11	TosH2ckL	FOSC↑ to CLKOUT↓ (1)	—	—	70	ns	VDD = 3.3-5.0V
OS12	TosH2ckH	FOSC↑ to CLKOUT↑ (1)	—	—	72	ns	VDD = 3.3-5.0V
OS13	TckL2ioV	CLKOUT↓ to Port out valid(1)	—	—	20	ns	
OS14	TioV2ckH	Port input valid before CLKOUT↑(1)	TOSC + 200 ns	—	—	ns	
OS15	TosH2ioV	Fosc↑ (Q1 cycle) to Port out valid	—	50	70*	ns	VDD = 3.3-5.0V
OS16	TosH2ioI	Fosc↑ (Q2 cycle) to Port input invalid (I/O in hold time)	50	—	—	ns	VDD = 3.3-5.0V
OS17	TioV2osH	Port input valid to Fosc↑ (Q2 cycle) (I/O in setup time)	20	—	—	ns	
OS18*	TioR	Port output rise time	— —	40 15	72 32	ns	VDD = 1.8V VDD = 3.3-5.0V
OS19*	TioF	Port output fall time	— —	28 15	55 30	ns	VDD = 1.8V VDD = 3.3-5.0V
OS20*	Tinp	INT pin input high or low time	25	—	—	ns	
OS21*	Tioc	Interrupt-on-change new input level time	25	—	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated.

Note 1: Measurements are taken in RC mode where CLKOUT output is 4 x TOSC.

FIGURE 30-8: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING



Note 1: Asserted low.

TABLE 30-5: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER AND BROWN-OUT RESET PARAMETERS

Standard Operating Conditions (unless otherwise stated) Operating Temperature -40°C ≤ TA ≤ +125°C							
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
30	TMCL	$\overline{\text{MCLR}}$ Pulse Width (low)	2	—	—	μs	
31	TWDTLP	Low-Power Watchdog Timer Time-out Period	12	16	20	ms	VDD = 3.3V-5V, 1:16 Prescaler used
32	TOST	Oscillator Start-up Timer Period(1)	—	1024	—	Tosc	
33*	TPWRT	Power-up Timer Period, $\overline{\text{PWRTE}}$ = 0	40	65	140	ms	
34*	TIOZ	I/O high-impedance from $\overline{\text{MCLR}}$ Low or Watchdog Timer Reset	—	—	2.0	μs	
35	VBOR	Brown-out Reset Voltage(2)	2.55 1.80	2.70 1.9	2.85 2.05	V V	BORV = 0 BORV = 1
36*	VHYST	Brown-out Reset Hysteresis	20	35	75	mV	-40°C to +85°C
37*	TBORDC	Brown-out Reset DC Response Time	1	3	35	μs	VDD ≤ VBOR

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: By design, the Oscillator Start-up (OST) counts the first 1024 cycles, independent of frequency.

2: To ensure these voltage tolerances, VDD and VSS must be capacitively decoupled as close to the device as possible. 0.1 μF and 0.01 μF values in parallel are recommended.

FIGURE 30-10: TIMER0 AND TIMER1 EXTERNAL CLOCK TIMINGS

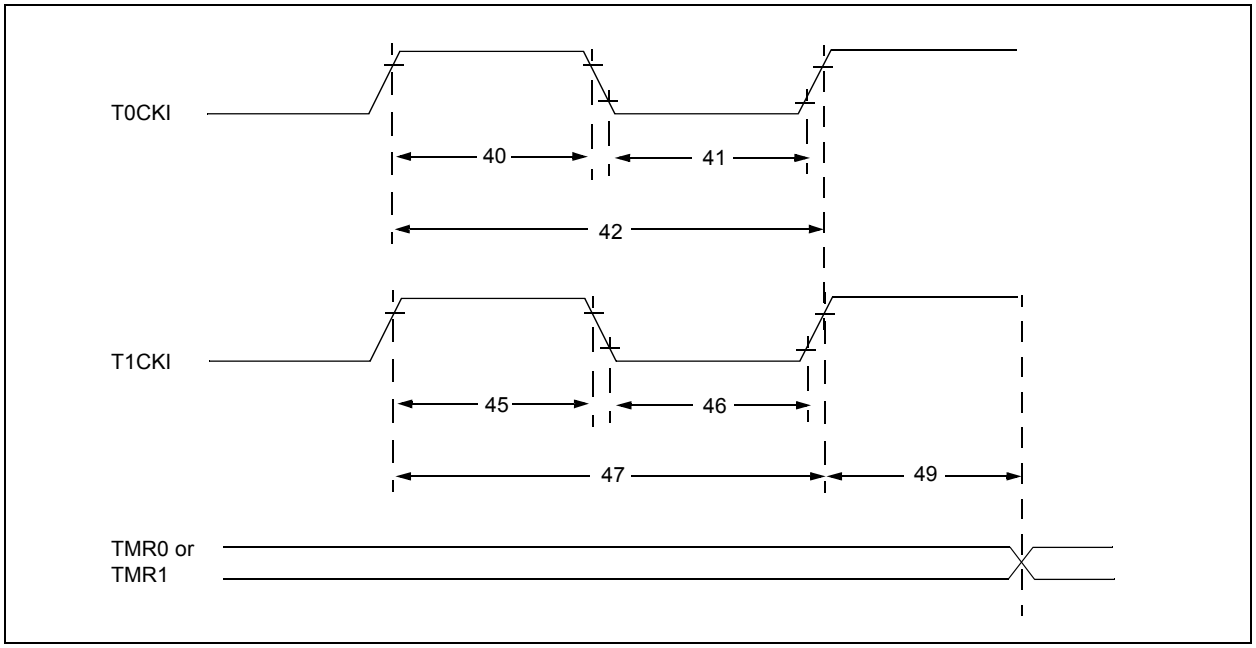


TABLE 30-22: MEMORY PROGRAMMING REQUIREMENTS FOR PIC16F1825/9-H (High Temp.)

PIC16F1825/9		Standard Operating Conditions: (unless otherwise stated) Operating Temperature: -40°C ≤ TA ≤ +150°C for High Temperature					
Param No.	Sym.	Characteristic	Min.	Typ.	Max.	Units	Conditions
		Data EEPROM Memory					
D116	ED	Byte Endurance	50K	—	—	E/W	-40°C to +150°C
D118	TDEW	Erase/Write Cycle Time	—	—	6.0	ms	-40°C to +150°C
D119	TRETD	Data Retention	—	20	—	Years	≤ 50K Programming cycles
		Program Flash Memory					
D121	EP	Cell Endurance	—	—	—	—	Programming the Flash memory above +125°C is not permitted
D124	TRETD	Data Retention	—	20	—	Years	

TABLE 30-23: OSCILLATOR PARAMETERS FOR PIC16F1825/9-H (High Temp.)

PIC16F1825/9			Standard Operating Conditions: (unless otherwise stated) Operating Temperature: -40°C ≤ TA ≤ +150°C for High Temperature					
Param No.	Sym.	Characteristic	Frequency Tolerance	Min.	Typ.	Max.	Units	Conditions
OS08	HFOSC	Int. Calibrated HFINTOSC Freq.(1)	±5%	—	16.0	—	MHz	-40°C ≤ TA ≤ 125°C VDD ≥ 2.5V
			±10%	—	16.0	—	MHz	-40°C ≤ TA ≤ 150°C VDD ≥ 2.5V
OS08A	MFOSC	Int. Calibrated MFINTOSC Freq.(1)	±5%	—	500	—	kHz	-40°C ≤ TA ≤ 125°C VDD ≥ 2.5V
			±10%	—	500	—	kHz	-40°C ≤ TA ≤ 150°C VDD ≥ 2.5V
OS09	LFOSC	Internal LFINTOSC Freq.	±35%	—	31	—	kHz	-40°C ≤ TA ≤ 150°C VDD ≥ 2.5V

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: To ensure these oscillator frequency tolerances, VDD and VSS must be capacitively decoupled as close to the device as possible. 0.1 µF and 0.01 µF values in parallel are recommended.

TABLE 30-24: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER AND BROWN-OUT RESET PARAMETERS FOR PIC16F1825/9-H (High Temp.)

PIC16F1825/9			Standard Operating Conditions: (unless otherwise stated) Operating Temperature: -40°C ≤ TA ≤ +150°C for High Temperature				
Param No.	Sym.	Characteristic	Min.	Typ.	Max.	Units	Conditions
31	TWDTLP	Low-Power Watchdog Timer Time-out Period (No Prescaler)	6	20	70	ms	VDD = 3.3V-5V 1:16 Prescaler used
35	VBOR	Brown-out Reset Voltage(1)	2.50 —	2.70 —	2.90 —	V —	BORV = 0 BORV = 1

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: To ensure these voltage tolerances, VDD and VSS must be capacitively decoupled as close to the device as possible. 0.1 µF and 0.01 µF values in parallel are recommended.

FIGURE 31-5: IDD TYPICAL, XT AND EXTRC OSCILLATOR, PIC16F1825/9 ONLY

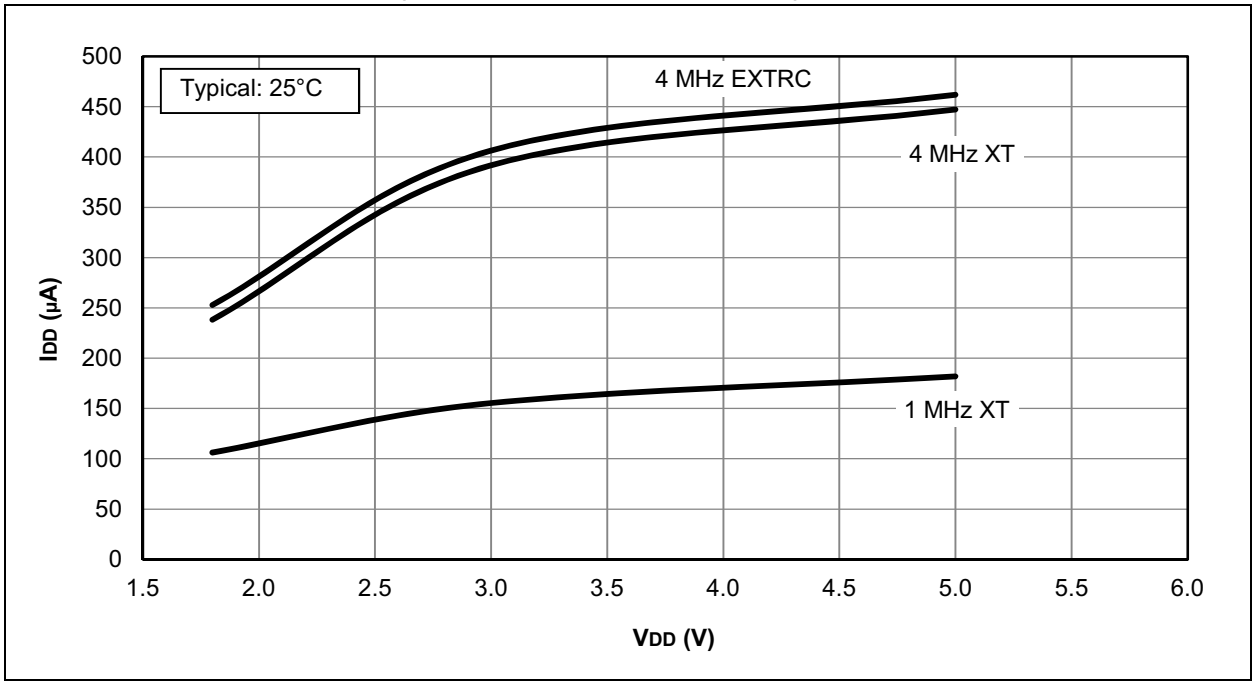


FIGURE 31-6: IDD MAXIMUM, XT AND EXTRC OSCILLATOR, PIC16F1825/9 ONLY

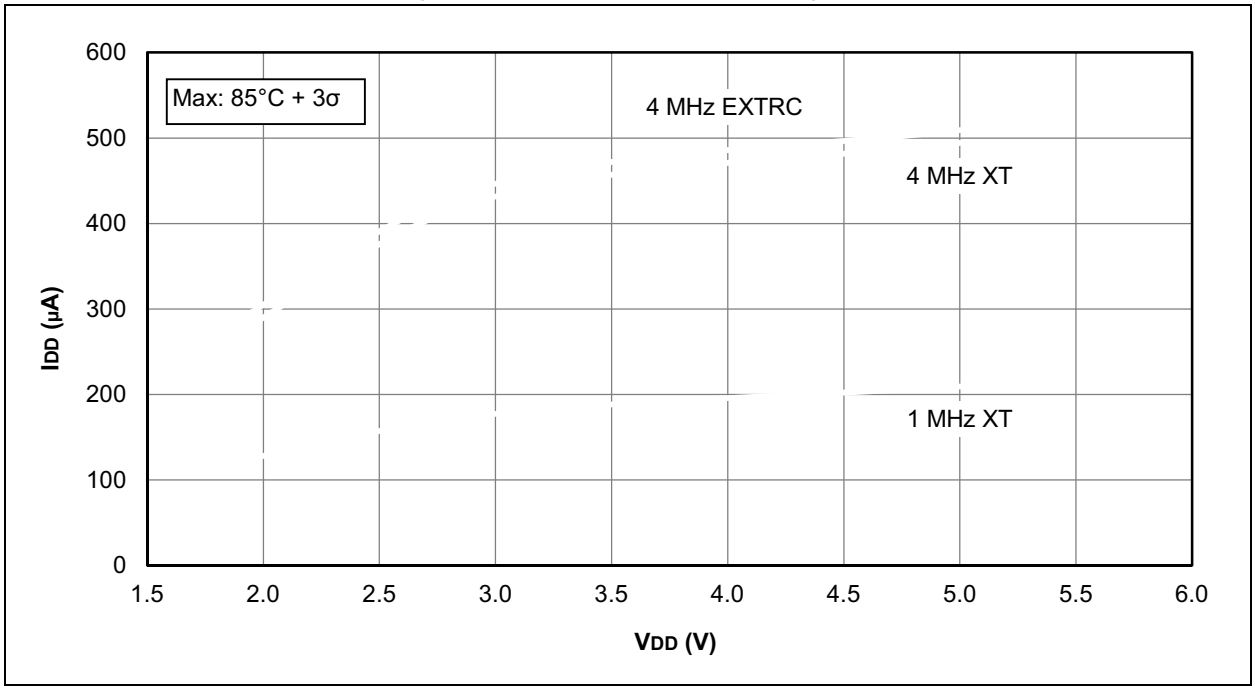


FIGURE 31-31: I_{PD}, CAPACITIVE SENSING (CPS) MODULE, LOW-CURRENT RANGE, CPSRM = 0, PIC16LF1825/9 ONLY

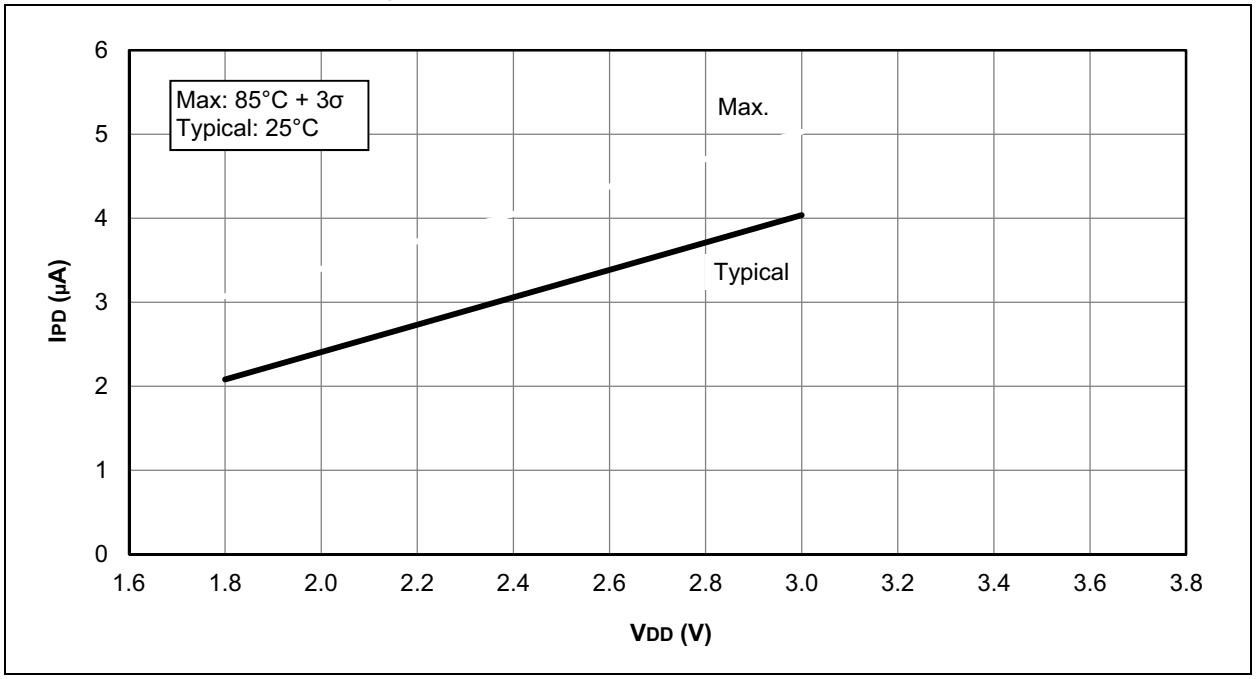


FIGURE 31-32: I_{PD}, CAPACITIVE SENSING (CPS) MODULE, LOW-CURRENT RANGE, CPSRM = 0, PIC16F1825/9 ONLY

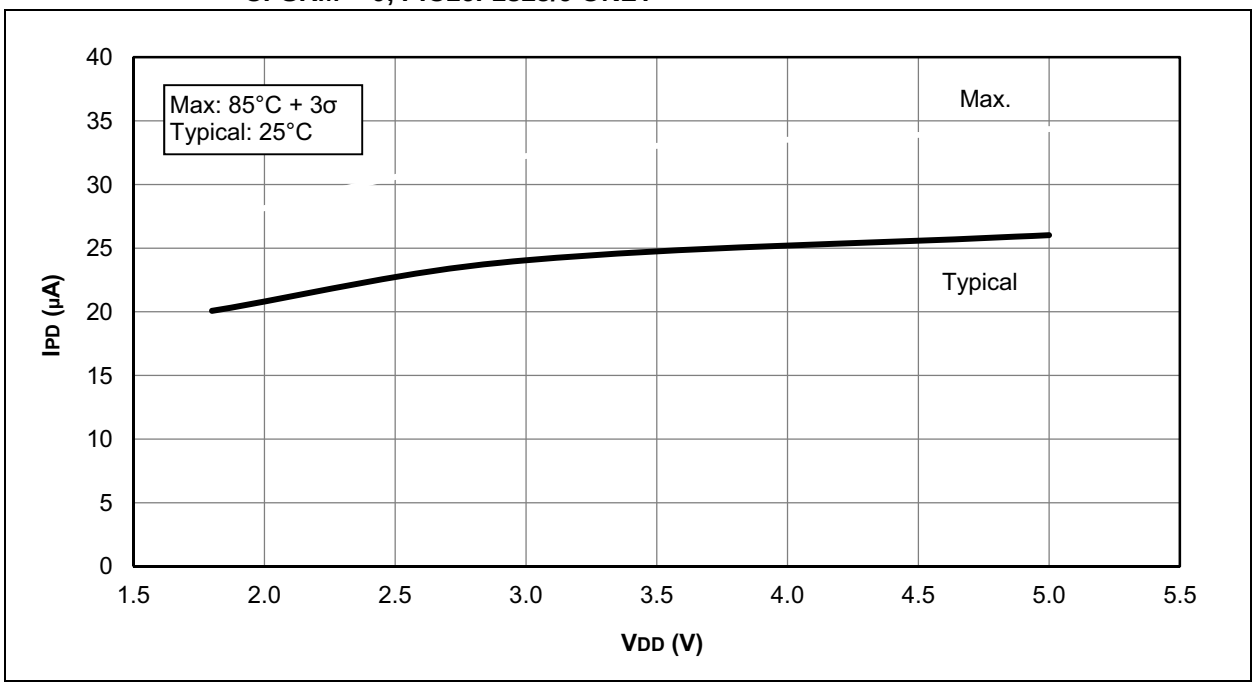


FIGURE 31-47: POR RELEASE VOLTAGE

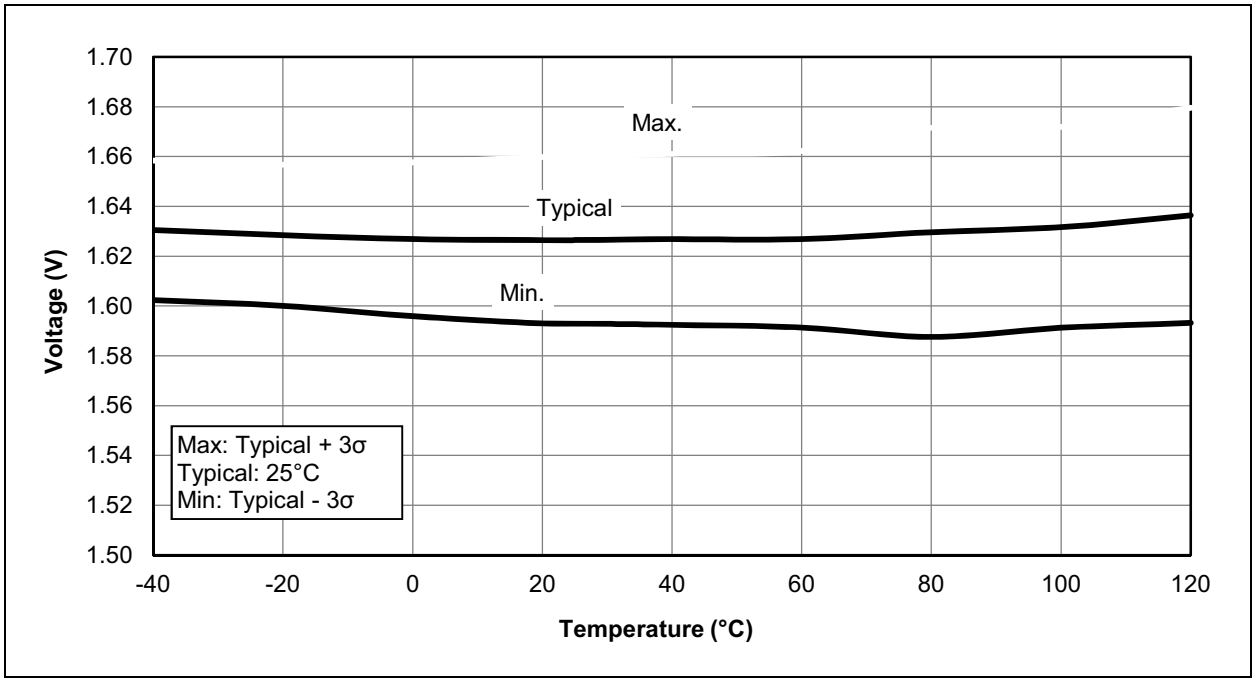
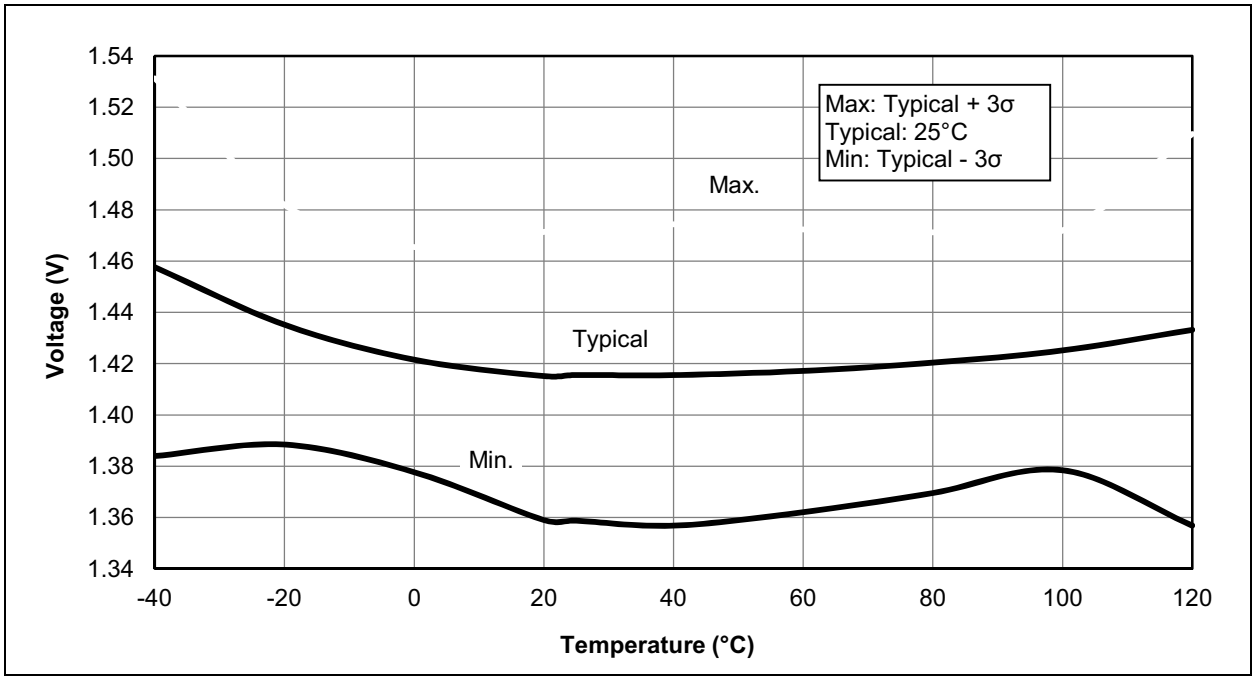


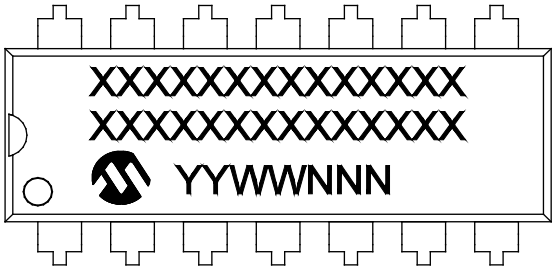
FIGURE 31-48: POR REARM VOLTAGE, PIC16F1825/9 ONLY



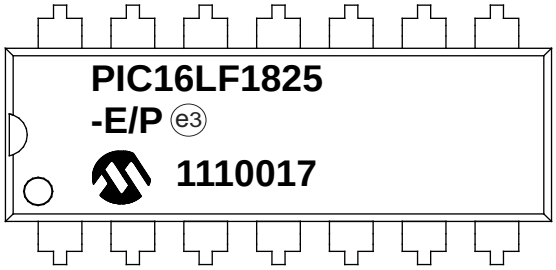
33.0 PACKAGING INFORMATION

33.1 Package Marking Information

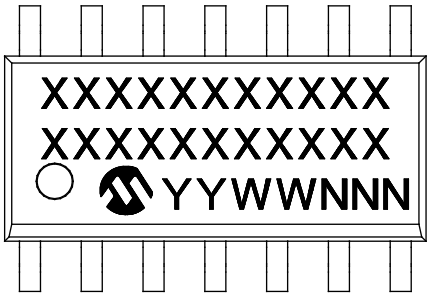
14-Lead PDIP (300 mil)



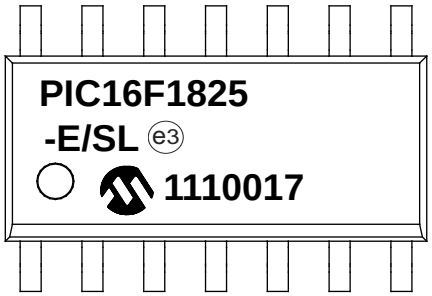
Example



14-Lead SOIC (3.90 mm)



Example

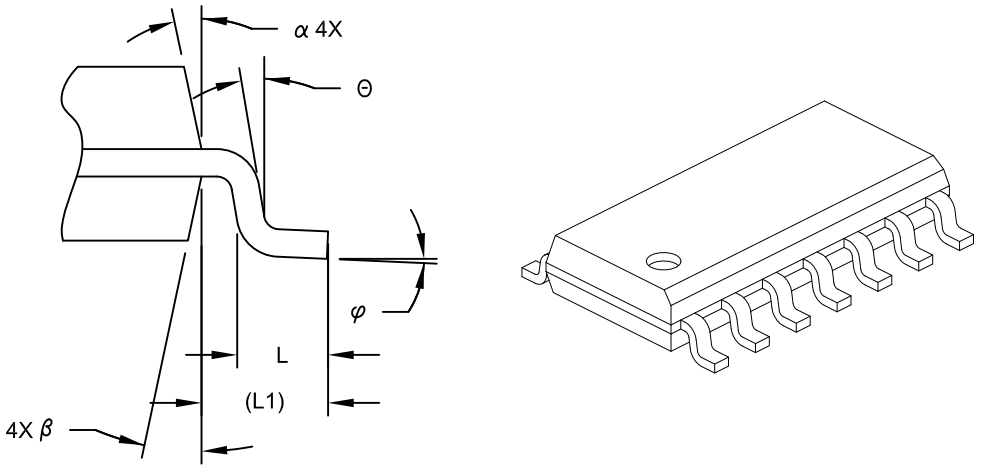


Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC® designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

14-Lead Plastic Small Outline (SL) - Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



VIEW C

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		14	
Pitch	e		1.27 BSC	
Overall Height	A	-	-	1.75
Molded Package Thickness	A2	1.25	-	-
Standoff §	A1	0.10	-	0.25
Overall Width	E		6.00 BSC	
Molded Package Width	E1		3.90 BSC	
Overall Length	D		8.65 BSC	
Chamfer (Optional)	h	0.25	-	0.50
Foot Length	L	0.40	-	1.27
Footprint	L1		1.04 REF	
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.10	-	0.25
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

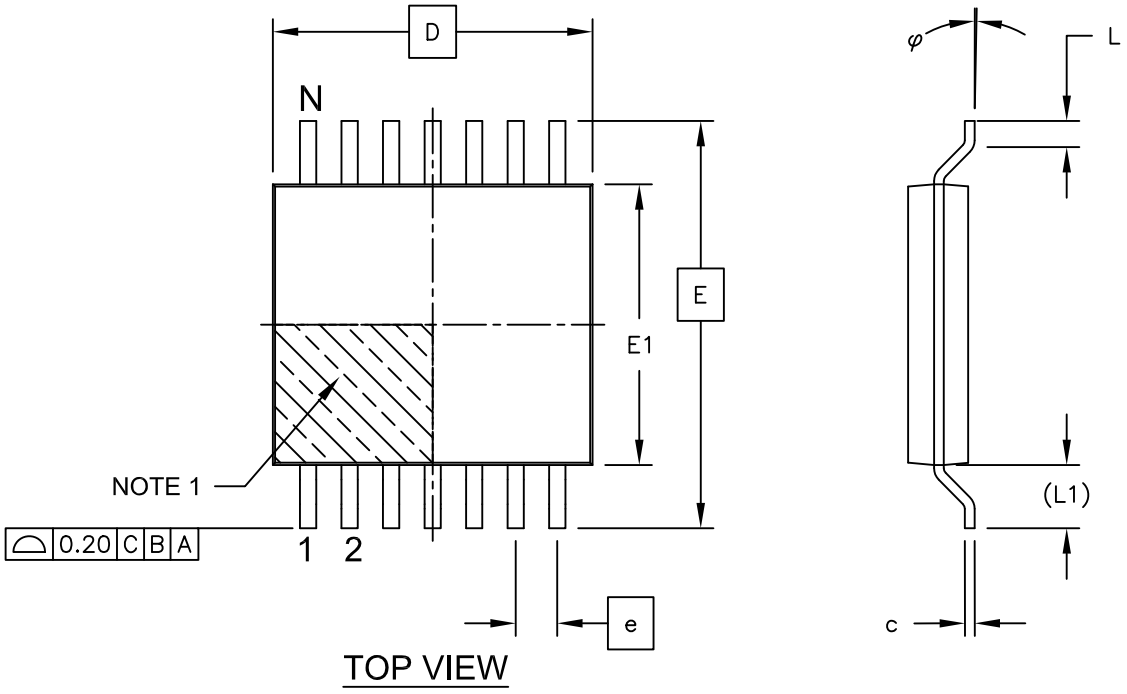
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

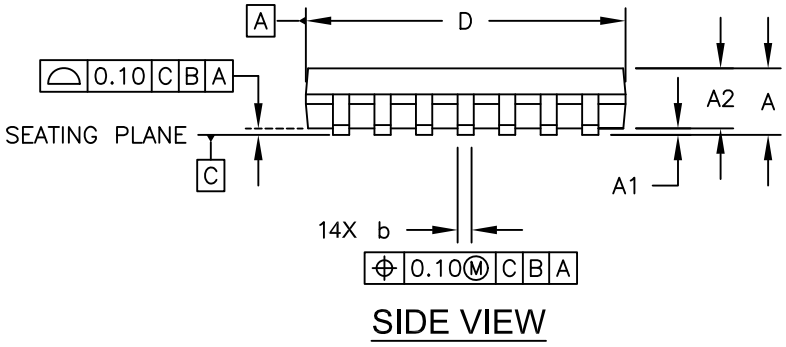
   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing No. C04-065C Sheet 2 of 2

14-Lead Plastic Thin Shrink Small Outline (ST) - 4.4 mm Body [TSSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging





Microchip Technology Drawing C04-087C Sheet 1 of 2